

Product Change Notification - RMES-23VKIG830

Date:

26 Jun 2019

Product Category:

Others; Ethernet Switches

Affected CPNs:



Notification subject:

CCB 3814 Initial Notice: Qualification of G631H mold compound material for selected Mircel products available in 128L PQFP (14x20x2.72mm) package at ASE assembly site.

Notification text:

PCN Status:

Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as

PCN # Affected CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of G631H mold compound material for selected Micrel products available in 128L PQFP (14x20x2.72mm) package at ASE assembly site.

Pre Change:

Using G700A mold compound material

Post Change:

Using G631H mold compound material

Pre and Post Change Summary:

	Pre Change	Post Change			
Assembly Site	ASE Kaohsiung (ASE)	ASE Kaohsiung (ASE)			
Wire material	Au	Au			
Die attach material	2288A	2288A			
Molding compound material	G700A	G631H			
Lead frame material	C7025	C7025			

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying G631H mold compound.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

July 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:



	June 2019				July 2019					
Workweek	22	23	24	25	26	27	28	29	30	31
Initial PCN Issue Date					X					
Qual Report Availability										X
Final PCN Issue Date										X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan

Revision History:

June 26, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_RMES-23VKIG830_Qual_Plan.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)						
KSZ8993						
KSZ8993I						
Date: Tuesday, June 25, 2019						